

AMENDMENTS TO THE ABSTRACT:

Please amend the Abstract originally appearing on page 18 of the application as follows:

ABSTRACT OF THE DISCLOSURE

A semiconductor device, such as an integrated circuit die, includes a plurality of bond pads on an active surface thereof electrically connected to internal circuitry of the semiconductor device, and a plurality of jumper pads on the active surface which are electrically isolated from internal circuitry of the die. The jumper pads effectively provide stepping stones for wire bonds to be made across the active surface between bond pads. The jumper pads may be formed directly on the semiconductor device or on a ~~non-conductive~~ nonconductive support structure that is attached to the semiconductor device.